IEEE Letters on EMC
Practice and Applications
(L-EMCPA)

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APPLICATION LETTERS on the
Special Issue - “Practical Applications and Advancements in Electromagnetic Shielding and Absorbers”

IEEE Letters on Electromagnetic Compatibility Practice and Applications (L-EMCPA) is a quarterly published letter journal that provides a rigorously peer-reviewed forum for rapid publication of **4 page letters** describing practice, lessons learned and applications of the disciplines electromagnetic compatibility (EMC) and signal and power integrity (SIPI) as well as all relevant methods to predict, assess and prevent electromagnetic interference (EMI) and increase device/product immunity.

In 2026 the L-EMCPA is going to publish a special issue on **Practical Applications and Advancements in Electromagnetic Shielding and Absorbers**. In recent decades, the rapid advancement of technology has led to a notable increase in electromagnetic interference (EMI) issues. The proliferation of interconnected devices and higher clock frequencies has amplified the risk of EMI, resulting in more complex electromagnetic compatibility (EMC) challenges. Effective EMC design practices are essential during both the design and development phases. Shielding is a key technique to address EMC problems, enhancing hardware immunity against electromagnetic (EM) phenomena and limiting emissions. Various research efforts and approaches have been developed to tackle specific issues, and numerous aspects are currently being explored globally. These include parameters for measuring shielding effectiveness, low-frequency shielding challenges, new materials, analysis methods, relevant standards, resonant enclosures, measurement techniques, absorber effectiveness, and more. Advancing the scientific foundation for shielding theory and practice is essential. This special issue on Shielding and Absorbers for practice and application aims to promote this field by providing a platform for inter-disciplinary researchers and practitioners to share recent progress and innovations. The scope of this

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special issue includes electromagnetic shielding and absorbers, which hold promise for advancing future EMC solutions. Publishable manuscripts may include, but are not limited to:

a) Materials for Electromagnetic Shielding and Absorbers
b) Shielding Enclosures theory and applications
c) Need for standardization on shielding and absorbers
d) Absorbers and
e) Measurement of Shielding / Absorbers Performance correlated to practice.

Authors are invited to submit manuscripts up to 4 pages in length, including title, author's affiliation, abstract, take home messages and figures via https://mc.manuscriptcentral.com/l-emcpa-ieee. Select the paper as "Special Issue paper"; insert only the following phrase "for Special Issue on Practical Applications and Advancements in Electromagnetic Shielding and Absorbers" in the cover letter field. A template is available on the EMC Society homepage (www.emcs.org) under publications.

Paper submission deadline:	**30 January 2026** (later submissions will not be accepted)
Planned publication date:	**September/December 2026**

Guest Editors:
- Dr. Pavithrakrishnan Radhakrishnan (Post-doc, Oklahoma State University, USA)
- Prof. Dr. Davy Pissoort (KU Leuven, Belgium)

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